502493906 09/12/2013

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Vincent Steffan Francischetti	09/04/2013
Gregory J. Wilson	09/04/2013
Kyle M. Hanson	09/04/2013
Paul Wirth	09/04/2013
Robert B. Moore	09/04/2013

RECEIVING PARTY DATA

Name:	APPLIED Materials, Inc.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14025678

CORRESPONDENCE DATA

Fax Number: 2063327198

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 310-788-9900

Email: patentprocurement@perkinscoie.com

Correspondent Name: PERKINS COIE LLP/SEMITOOL

Address Line 1: PO BOX 1208

Address Line 4: SEATTLE, WASHINGTON 98111-1208

ATTORNEY DOCKET NUMBER:	63857.8295.US00
NAME OF SUBMITTER:	Kenneth H. Ohriner
Signature:	/Kenneth H. Ohriner/

502493906 REEL: 031197 FRAME: 0197

OP \$40.00 14025678

Date:	09/12/2013
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 5 source=8295_Decls_Assignments#page1.tif source=8295_Decls_Assignments#page2.tif source=8295_Decls_Assignments#page3.tif source=8295_Decls_Assignments#page4.tif source=8295_Decls_Assignments#page5.tif	

Title of Invention:	ANNEAL MODULE FOR SEMICONDUCTOR WAFERS	
As the below named inve	ntor, I hereby declare that:	
This declaration is directed to:	X The attached application, or	
	United States application or PCT international application number filed on	
The above-identified app	lication was made or authorized to be made by me.	
I believe that I am the ori	ginal inventor or an original joint inventor of a claimed invention in the application.	
I hereby state that I have claims.	reviewed and understand the contents of the above-identified specification, including the	
I acknowledge the duty to	o disclose information which is material to patentability as defined in 37 CFR 1.56.	
WHEREAS, APPLIED Materials, Inc., a corporation of the State of Delaware (hereinafter referred to as "ASSIGNEE") having a place of business at: 3050 Bowers Avenue, Santa Clara, CA 95054, desires to acquire the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;		
I, by these presents, do so invention in the United S claim priority under the t Arrangements from the a Patent which may be gran	E, for valuable consideration, the receipt and sufficiency of which I hereby acknowledge, ell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said tates and its territorial possessions and in all foreign countries (including the right to erms of the International Convention and other relevant International Treaties and foresaid application) and the entire right, title and interest in and to any and all Letters need therefor in the United States and its territorial possessions and in any and all foreign my and all divisions, reissues, continuations, substitutions and renewals thereof.	
I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.		
Further, I agree that I will communicate to said ASSIGNEE or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.		
	at any willful false statement made in this declaration is punishable under 18 U.S.C. ment of not more than five (5) years, or both.	
LEGAL NAME OF IN	VENTOR: VINCENT STEFFAN FRANCISCHETTI	

63857-8295.US00/LEGAL27741657.1

Title of Invention:	ANNEAL MODULE FOR SEMICONDUCTOR WAFERS	
As the below named inve	entor, I hereby declare that:	
This declaration is directed to:	X The attached application, or United States application or PCT international application number filed on	
The above-identified app	lication was made or authorized to be made by me.	
	ginal inventor or an original joint inventor of a claimed invention in the application.	
I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.		
I acknowledge the duty to	o disclose information which is material to patentability as defined in 37 CFR 1.56.	
WHEREAS, APPLIED Materials, Inc., a corporation of the State of Delaware (hereinafter referred to as "ASSIGNEE") having a place of business at: 3050 Bowers Avenue, Santa Clara, CA 95054, desires to acquire the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;		
NOW, THEREFORE, for valuable consideration, the receipt and sufficiency of which I hereby acknowledge, I, by these presents, do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.		
I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.		
Further, I agree that I will communicate to said ASSIGNEE or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF IN	VENTOR: GREGORY J. WILSON	
Signature:	hayy below Date: 9/4/13	

63857-8295.US00/LEGAL27717831.1

Title of Invention:	ANNEAL MODULE FOR SEMICONDUCTOR WAFERS	
As the below named inve	entor, I hereby declare that:	
This declaration is	X The attached application, or	
directed to:	United States application or PCT international application number filed on	
The above-identified app	lication was made or authorized to be made by me.	
I believe that I am the ori	ginal inventor or an original joint inventor of a claimed invention in the application.	
I hereby state that I have claims.	reviewed and understand the contents of the above-identified specification, including the	
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I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.		
Further, I agree that I will communicate to said ASSIGNEE or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF IN	VENTOR: / KYLE M. HANSON	
Signature:	11. Land Date: 9/4/13	

63857-8295.US00/LEGAL27717847.1

Title of Invention:	ANNEAL MODULE FOR SEMICONDUCTOR WAFERS	
As the below named inve	entor, I hereby declare that:	
This declaration is directed to:	X The attached application, or United States application or PCT international application number filed on	
The above-identified app	lication was made or authorized to be made by me.	
, ,	ginal inventor or an original joint inventor of a claimed invention in the application.	
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NOW, THEREFORE, for valuable consideration, the receipt and sufficiency of which I hereby acknowledge, I, by these presents, do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.		
I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.		
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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF IN	Date: September 4, 2013	

63857-8295.US00/LEGAL27717856.1

Title of Invention:	ANNEAL MODULE FOR SEMICONDUCTOR WAFERS
As the below named inv	/entor, I hereby declare that:
This declaration is	X The attached application, or
directed to:	United States application or PCT international application number filed on
The above-identified ap	plication was made or authorized to be made by me.
I believe that I am the o	riginal inventor or an original joint inventor of a claimed invention in the application.
I hereby state that I have claims.	e reviewed and understand the contents of the above-identified specification, including the
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"ASSIGNEE") having a the entire right, title and	Materials, Inc., a corporation of the State of Delaware (hereinafter referred to as a place of business at: 3050 Bowers Avenue, Santa Clara, CA 95054, desires to acquire linterest in and to said invention and in and to any Letters Patent that may be granted States and its territorial possessions and in any and all foreign countries;
I, by these presents, do invention in the United claim priority under the Arrangements from the Patent which may be gr	EE, for valuable consideration, the receipt and sufficiency of which I hereby acknowledge, sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said States and its territorial possessions and in all foreign countries (including the right to terms of the International Convention and other relevant International Treaties and aforesaid application) and the entire right, title and interest in and to any and all Letters anted therefor in the United States and its territorial possessions and in any and all foreign any and all divisions, reissues, continuations, substitutions and renewals thereof.
and any and all foreign the assignee of my entin ASSIGNEE, its (his) su	and request the Patent Office Officials in the United States and its territorial possessions countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as re right, title and interest in and to the same, for the sole use and behoof of said ccessors and assigns, to the full end of the term for which said Letters Patent may be tirely as the same would have been held by me had this Assignment and sale not been
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LEGAL NAME ØF IN	EVENTOR: ROBERT B. MOORE
Signature:	Date: 9/4/2013

63857-8295.US00/LEGAL27717860.1

PATENT REEL: 031197 FRAME: 0203

RECORDED: 09/12/2013